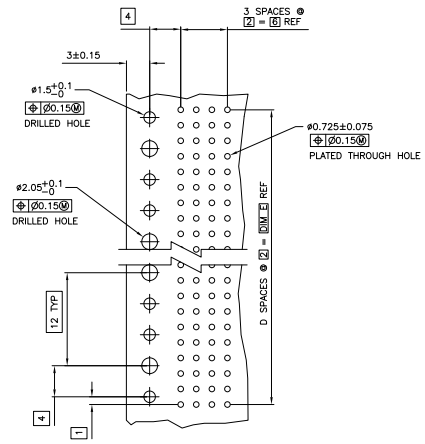
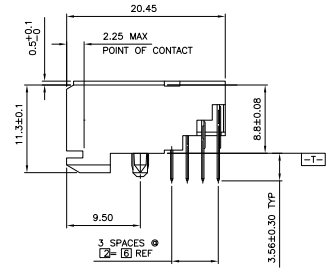
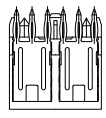
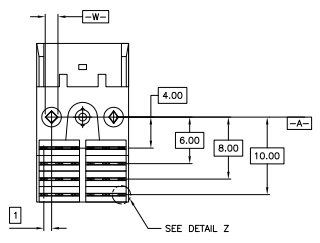
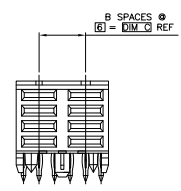
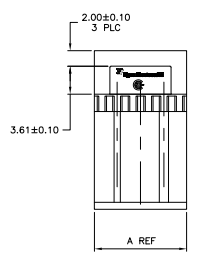
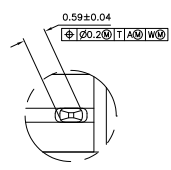


REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00				
PZ		REVISED PER ECO-08-009111			



△ HOUSING MATERIAL: LIQUID CRYSTAL POLYMER.
 △ CONTACT MATERIAL: PHOSPHOR-BRONZE.
 △ CONTACT FINISH:
 UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
 ON MATING SURFACES:
 FLASH GOLD PER ASTM B 488, OVER
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
 0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.
 ON LEADS:
 0.00127 MIN TIN-LEAD OVER UNDERPLATE.
 LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.



DETAIL Z
 SCALE 20:1

RECOMMENDED CIRCUIT PATTERN
 PER IPC-D300 TYPE II, CLASS C
 (COMPONENT SIDE)

10	5	6	1	11.88	△	8	536614-1
E	D	C	B	A	FINISH	NO OF POSN	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 11/26/01							
DESIGNER: J. BENDER				DATE: 02/26/01			
CHECKER: J. BENDER				DATE: 02/26/01			
DRAWN: J. BENDER				DATE: 02/26/01			
PROJECT: Z-PACK 2mm FB, POWER MODULE, RCPT. ASSY.				REV: 1			
PART: Z-PACK 2mm FB, POWER MODULE, RCPT. ASSY.				REV: 1			
CUSTOMER: TYSO ELECTRONICS CORPORATION				REV: 1			
CUSTOMER DRAWING				REV: 1			